

Method of Improving the Wafer to Wafer Uniformity and Defectivity of a Deposited Dielectric Film

Abstract of the Disclosure

A method and apparatus are included that provide an improved deposition process for a Tunable Etch Resistant ARC (TERA) layer with improved wafer to wafer uniformity and reduced particle contamination. More specifically, the processing chamber is seasoned to reduce the number of contaminant particles generated in the chamber during the deposition of the TERA layer and improve wafer to wafer uniformity. The apparatus includes a chamber having an upper electrode at least one RF source, a substrate holder, and a showerhead for providing multiple precursors and process gasses.